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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Randall J. Stutzman, et al.

Date: September 1, 2004

Serial No.: 10/634,554

IBM Corporation

Filed: August 5, 2003

Intellectual Property Law

Dept. 1Q0A/040-3, 1701 North Street
Endicott, New York 13760

For: **FLIP CHIP PACKAGE WITH HEAT SPREADER ALLOWING MULTIPLE
HEAT SINK ATTACHMENT**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Transmitted herewith for filing is an **Amendment** in the above-identified Application.

X No additional fee is required.

X The fee has been calculated as shown below:

(Col. 1)	(Col. 2)	(Col. 3)
Claims Remaining After Amendment		Highest No. Previously Paid For
Total * 20	Minus	** 20
<hr/> 1st Presentation of Multiple Dependent Claims		
Independent * 4	Minus	*** 3
		= 1

Other Than Small Entity

Rate	Additional Fee
x \$ 18.00	. \$ 0.00
x \$ 86.00	. \$ 86.00
. \$290.00	. \$ 0.00
Total	. \$ 86.00

* If the entry in Col. 1 is less than the entry in Col. 2, write "0" in Col. 3.

** If the "Highest No. Previously Paid For" IN THIS SPACE is less than 20, write "20" in this space.

*** If the "Highest No. Previously Paid For" (Total or Independent) is the highest number found from the equivalent box in Col. 1 of a prior amendment or the number of claims originally filed.

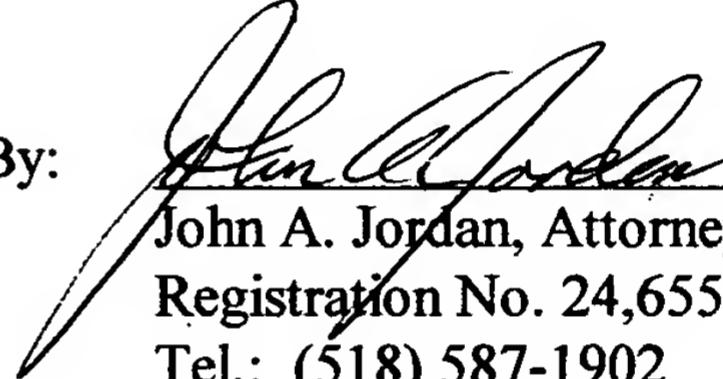
X Please charge Deposit Account No. 09-0457 in the amount of \$0.00. A duplicate copy of this sheet is enclosed.

X The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit overpayment to Deposit Account No. 09-0457. A duplicate copy of this sheet is enclosed.

X Any additional filing fees required under 37 CFR §1.16. X Any patent application processing fees under 37 CFR §1.17.

Respectfully submitted,

Randall J. Stutzman, et al.

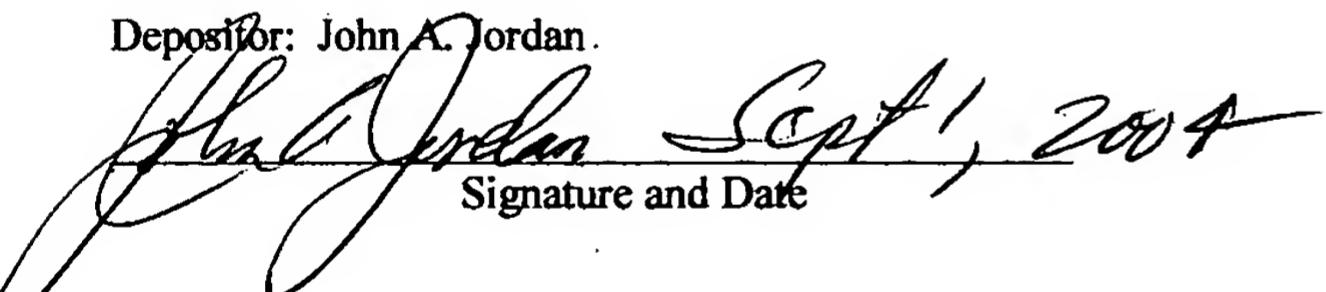
By: 

John A. Jordan, Attorney
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Tel.: (518) 587-1902

CERTIFICATE OF MAILING UNDER 37 CFR 1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on September 1, 2004.

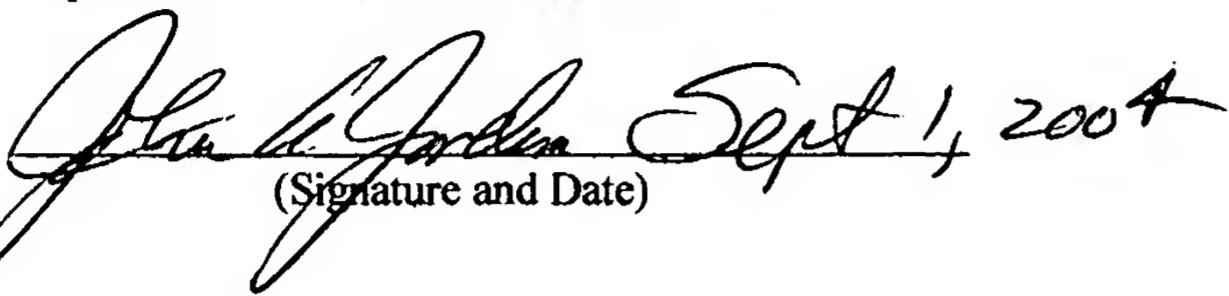
Depositor: John A. Jordan.


Signature and Date



I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE AS FIRST CLASS MAIL IN AN ENVELOPE ADDRESSED TO: COMMISSIONER FOR PATENTS, P.O. BOX 1450, ALEXANDRIA, VA 22313-1450, ON September 1, 2004.

Depositor: John A. Jordan


John A. Jordan Sept 1, 2004
(Signature and Date)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

<u>In Re Application of</u>	:	September 1, 2004
<u>Randall J. Stutzman, et al.</u>	:	Examiner: B.L. Chervinsky
<u>Serial No.: 10/634,554</u>	:	Confirmation No.: 6025
<u>Filed: August 5, 2003</u>	:	Art Unit: 2835
<u>Title: FLIP CHIP PACKAGE WITH HEAT SPREADER ALLOWING MULTIPLE HEAT SINK ATTACHMENT</u>	:	IBM Corporation Intellectual Property Law Dept. 1Q0A/040-3, 1701 North St. Endicott, New York 13760

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Examiner's Office Action of July 20, 2004, please amend the application as follows:

09/07/2004 MAHMED1 00000032 090457 10634554
01 FC:1201 86.00 DA

END920030014US1

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